



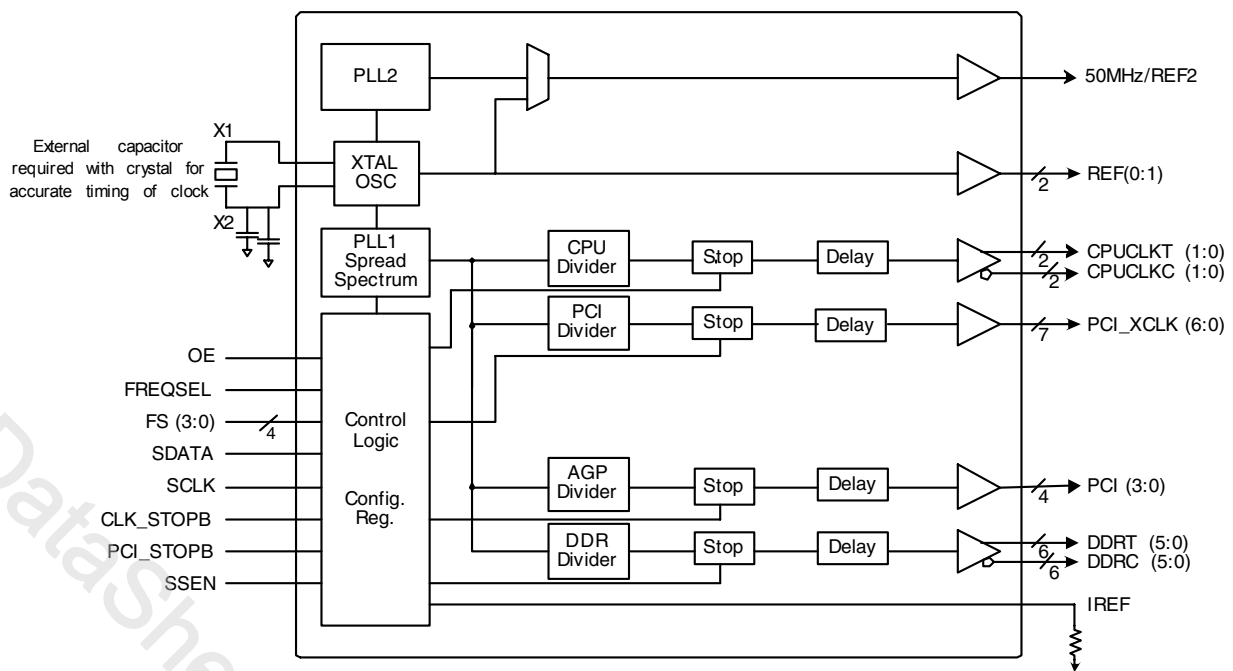
Description

The MK1493-02A is a general purpose clock generator that provides an integrated clocking solution for PCI/Networking applications. It provides two pairs of differential CPU clocks, four PCI clocks, seven PCI_X clocks, two reference clocks, additional clock selectable from REF/50 MHz, and six pairs of SSTL2 DDR at 2.5 V. **All complementary outputs operate only from a 2.5 V power supply.**

Input/Output Features

- Packaged in 56-pin TSSOP package
- 2 - Pairs of differential CPU clocks (differential current mode)
- 4 - PCI @ 3.3 V
- 7 - PCI_X @ 3.3 V
- 2 - REF @ 3.3 V, Fixed
- 6 - Pairs of differential SSTL2 DDR @ 2.5 V
- 1 - REF/50 MHz, selectable
- Spread spectrum for EMI control
- Supports SMBUS index read/write and blocks read/write operations
- Uses external 25 or 50 MHz crystal or clock
- CPU output jitter <125 ps
- PCI cycle to cycle output jitter <250 ps
- DDR cycle to cycle output jitter <150 ps

Block Diagram





Pin Assignment

VDDAND	1	56	VSSAND
X1	2	55	IREF
X2	3	54	OE
REF2_50M	4	53	CPUT0
VDDREF	5	52	CPUC0
VSSREF	6	51	VSSCPU
FREQSEL_REF0	7	50	VDDCPU
REF1	8	49	CPUT1
SCL	9	48	CPUC1
SDA	10	47	VSSDR0
PCI_XSTPB	11	46	VDDDR0
CLKSTPB	12	45	DDRT0
PCI0	13	44	DDRC0
PCI1	14	43	DDRT1
PCI2	15	42	DDRC1
PCI3	16	41	VSSDR1
VDDPCI	17	40	VDDDR1
VSSPCI	18	39	DDRT2
VSSPCI_X2	19	38	DDRC2
VDDPCI_X2	20	37	DDRT3
FS0_PCI_X0	21	36	DDRC3
FS1_PCI_X1	22	35	VDDDR2
FS2_PCI_X2	23	34	VSSDR2
FS3_PCI_X3	24	33	DDRT4
SSEN_PCI_X4	25	32	DDRC4
PCI_X5	26	31	DDRT5
PCI_X6	27	30	DDRC5
VSSPCI_X1	28	29	VDDPCI_X1

56 pin 240mil 0.50 mm pitch TSSOP

Functionality Table

F _{IN} MHz	FS3	FS2	FS1	FS0	CPUCLK MHz	DDR MHz	PCI MHz	PCI_X MHz
50	0	1	0	0	33	33	33	33
50	0	1	0	1	100	133	33	33
25	0	1	1	0	33	33	33	33
25	0	1	1	1	33	33	33	133
25 ¹	1	0	0	0	100 ¹	200 ¹	66 ¹	33 ¹
25	1	0	0	1	200	200	66	33
25	1	0	1	0	133	133	33	66
25	1	0	1	1	133	133	33	33
25	1	1	0	0	133	133	66	66
25	1	1	0	1	150	150	33	33
25	1	1	1	0	125	125	33	33
25	1	1	1	1	166	166	33	33

¹ Default start Output Clock settings,

33M=33.33 MHz, 66M=66.66 MHz, 133M=133.33 MHz.



Pin Descriptions

Pin	Pin Name	Pin Type	Pin Description
1	VDDAND	Power	Analog and digital power supply 3.3 V.
2	X1/CLK	XI	Crystal connection/input clock. Connect to a 25 MHz fundamental mode crystal.
3	X2	XO	Connect to a 25 MHz fundamental mode crystal or leave unconnected if X1 is a
4	REF2_50M	Output	REF2 or 50 MHz output.
5	VDDREF	Power	Power supply for REF outputs.
6	VSSREF	Power	Ground for REF outputs.
7	FREQSEL_REF0	I/O	Input frequency select input pin for 50 MHz/ REF2 (0=50 MHz select, 1=REF2 select). Output - REF0.(Internal Pull up resistor of 120K ohms see for page 21)
8	REF1	Output	REF1 clock output.
9	SCL	I/O	Clock pin for SMBUS circuitry. 5 V tolerant.
10	SDA	Input	Data pin for SMBUS circuitry. 5 V tolerant.
11	PCI_XSTPB	Input	Asynchronous input Stops all PCI_XCLK at logic level 0 when pulled low.(Internal pull up resistor 120K)
12	CUP_STPB	Input	Asynchronous input halts CPU , DDR and PCI clocks at logic 0 when driven low. S. (Internal pull up resistor 120K see page 21)
13	PCI0	Output	PCI Output clock 0.
14	PCI1	Output	PCI Output clock 1.
15	PCI2	Output	PCI Output clock 2.
16	PCI3	Input	PCI Output clock 3.
17	VDDPCI1	Power	Power supply for PCI clocks.
18	VSSPCI1	Power	Ground supply for PCI clocks.
19	VSSPCI_X2	Power	Ground for PCI_X clocks.
20	VDDPCI_X2	Power	Power supply for PCI_X clocks.
21	FS0_PCI_X0	I/O	FS0 input/PCI_X0 output. (Internal Pull Down resistor 120K , see page 21).
22	FS1_PCI_X1	I/O	FS1 input/PCI_X1 output. (Internal Pull Down resistor 120K , see page 21)
23	FS2_PCI_X2	I/O	FS2 input/PCI_X2 output. (Internal Pull Down resistor 120K , see page 21).
24	FS3_PCI_X3	I/O	FS3 input/PCI_X3 output. (Internal Pull up resistor 120K , see page 21).
25	SSEN_PCI4	I/O	Spread spectrum enable (0=SS disabled, 1=enabled). PCI clock output. (Internal pull down resistor 120K see page 21)
26	PCI_X5	Output	PCI_X clock output.
27	PCI_X6	Output	PCI_X clock output.
28	VSSPCI_X1	Power	Ground for PCI clocks.
29	VDDPCI_X1	Power	Power supply for PCI clocks.
30	DDRC5	Output	Complementary clock output of DDRT5.
31	DDRT5	Output	True clock output of DDRT5.
32	DDRC4	Output	Complementary clock output of DDRT4.
33	DDRT4	Output	True clock output of DDRT4.
34	VSSDR2	Power	Ground for DDR clocks.
35	VDDDR2	Power	Power supply for DDR clocks (2.5 V only for complementary outputs).
36	DDRC3	Output	Complementary clock output of DDRT3.



Pin	Pin Name	Pin Type	Pin Description
37	DDRT3	Output	True clock output of DDRT3.
38	DDRC2	Output	Complementary clock output of DDRT2.
39	DDRT2	Output	True clock output of DDRT2.
40	VDDDR1	Power	Power supply for DDR clocks 2.5 V only for complementary outputs. (Can use 3.3 V supply for single ended outputs)
41	VSSDR1	Power	Ground for DDR clocks.
42	DDRC1	Output	Complementary clock output of DDRT1.
43	DDRT1	Output	True clock output of DDRT1.
44	DDRC0	Output	Complementary clock output of DDRT0.
45	DDRT0	Output	True clock output of DDRT0.
46	VDDDR0	Power	Power supply for DDR clocks 2.5 V only for complementary outputs). (Can use 3.3 V supply for single ended outputs)
47	VSSDR0	Power	Ground for DDR clocks.
48	CPUC1	Output	Complementary CPU clock output.
49	CPUT1	Output	True CPU clock output.
50	VDDCPU	Power	Power supply for CPU Clocks 3.3 V.
51	VSSCPU	Power	Ground for CPU clocks.
52	CPUC0	Output	Complementary CPU clock output.
53	CPUT0	Output	True CPU clock output.
54	OE	Input	Enables all outputs when high, tri-state outputs when low. Pull-up.
55	IREF	Output	A precision resistor connected to ground establishes the external reference current.
56	VSSAND	Power	Analog and digital ground power supply.



General SMBUS Serial Interface Info

General SM-Bus Serial Interface Information

How to Write:

- Controller (host) sends a start bit
- Controller (host) sends the write address D2 (H)
- ICS clock will **acknowledge**
- Controller (host) sends the beginning byte location = **N**
- ICS clock will **acknowledge**
- Controller sends Byte Count **X**
- ICS clock will **acknowledge**
- Controller (host) starts sending Byte **N through Byte N+X-1**
- ICS clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

How to Read:

- Controller (host) will send a start bit
- Controller (host) sends the write address D2 (H)
- ICS clock will **acknowledge**
- Controller (host) sends the beginning Byte location = **N**
- ICS clock will **acknowledge**
- Controller (host) will send a repeat start bit
- Controller (host) sends the read address Byte D3 (H)
- ICS clock will **acknowledge**
- ICS clock will send the data Byte count = **X**
- ICS clock sends Byte **N**
- ICS clock sends Byte **N+X-1**
- Controller (host) will need to acknowledge each Byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Write Operation		
Controller (Host)		ICS (Slave/Receiver)
T	starT	
Slave Address D2 (H)	WR	
Beg Location = N		ACK
Data Byte Count = X		ACK
Beginning Byte N		ACK
O	X Byte	O
O		O
O		O
Byte N + X - 1		ACK
P	stoP	

Index Block Read Operation		
Controller (Host)		ICS (Slave/Receiver)
T	starT bit	
Slave Address D2 (H)	WR =0	
Beginning Loc = N		ACK
RT		ACK
Slave Address D2 (H)	repeat starT RD =1	
ACK		ACK
ACK		Data Byte Count=X
ACK		Beginning Byte N
O	X B Y T E S	O
O		O
O		O
O		O
Byte N + X - 1		
N	NAK	
P	stoP bit	



Serial Configuration Command Bitmap Byte 0: Functionary and frequency select register (default = 0)

Bit	Description												
	SSEN	FS3	FS2	FS1	FS0	CPUCLK (MHz)	DDR (MHz)	PCI (MHz)	PCI_X	F in	DDR Diff Out	Spread Percentage	Power up
	Bit2	Bit7	Bit6	Bit5	Bit4								
0	0	0	0	0	0	Reserved					N	N	
0	0	0	0	0	1	Reserved					N	N	
0	0	0	0	1	0	Reserved					N	N	
0	0	0	0	1	1	Reserved					N	N	
0	0	0	1	0	0	33	33	33	33	50	N	N	
0	0	0	1	0	1	100	133	33	33	50	N	N	
0	0	0	1	1	0	33	33	33	33	25	N	N	
0	0	0	1	1	1	33	33	33	133	25	N	N	
0	1	0	0	0	0	100	200	66	33	25	Y	N	Default
0	1	0	0	1	1	200	200	66	33	25	Y	N	
0	1	0	1	0	0	133	133	33	66	25	Y	N	
0	1	0	1	1	1	133	133	33	33	25	Y	N	
0	1	1	0	0	0	133	133	66	66	25	Y	N	
0	1	1	0	1	1	150	150	33	33	25	Y	N	
0	1	1	1	1	0	125	125	33	33	25	Y	N	
0	1	1	1	1	1	166	166	33	33	25	Y	N	
1	0	0	0	0	0	Reserved					N	(1% down spread)	
1	0	0	0	0	1	Reserved					N	(1% down spread)	
1	0	0	0	1	0	Reserved					N	(1% down spread)	
1	0	0	0	1	1	Reserved					N	(1% down spread)	
1	0	1	0	0	0	33	33	33	33	50	N	(1% down spread)	
1	0	1	0	1	1	100	133	33	33	50	N	(1% down spread)	
1	0	1	1	0	0	33	33	33	33	25	N	(1% down spread)	
1	0	1	1	1	1	33	33	33	133	25	N	(1% down spread)	
1	1	0	0	0	0	100	200	66	33	25	Y	(1% down spread)	
1	1	0	0	1	1	200	200	66	33	25	Y	(1% down spread)	
1	1	0	1	0	0	133	133	33	66	25	Y	(1% down spread)	
1	1	0	1	1	1	133	133	33	33	25	Y	(1% down spread)	
1	1	1	0	0	0	133	133	66	66	25	Y	(1% down spread)	
1	1	1	0	1	1	150	150	33	33	25	Y	(1% down spread)	
1	1	1	1	1	0	125	125	33	33	25	Y	(1% down spread)	
1	1	1	1	1	1	166	166	33	33	25	Y	(1% down spread)	
Bit3	0 - Frequency is selected by hardware select, Latched inputs 1 - Frequency is selected by Bit 2, 7:4												
Bit 1	RESERVED												
Bit 0	0 - Running 1 - Tristate all outputs												

**Byte 1: Output Enable Register**

(1 = enable, 0 = tristate)

Bit	Pin #	PUP	Description
Bit7	-	X	RESERVED
Bit6	49, 48	1	CPUT/C1
Bit5	53, 52	1	CPUT/C0
Bit4	25	X	SSEN Read back
Bit3	24	X	FS3 Read back
Bit2	23	X	FS2 Read back
Bit1	22	X	FS1 Read back
Bit0	21	X	FS0 Read back

Byte 2: Output Enable Register

(1 = enable, 0 = tristate)

Bit	Pin #	PUP	Description
Bit7	-	X	RESERVED
Bit6	27	1	PCI_X6
Bit5	26	1	PCI_X5
Bit4	25	1	PCI_X4
Bit3	24	1	PCI_X3
Bit2	23	1	PCI_X2
Bit1	22	1	PCI_X1
Bit0	21	1	PCI_X0

Byte 3: Output Enable Register

(1 = enable, 0 = tristate)

Bit	Pin #	PUP	Description
Bit7	42, 43, 44, 45	1	DDRT/C (0:1)
Bit6	36, 37, 38, 39	1	DDRT/C (2:3)
Bit5	30, 31, 32, 33	1	DDRT/C (4:5)
Bit4	-	-	RESERVED
Bit3	16	1	PCI3
Bit2	15	1	PCI2
Bit1	14	1	PCI1
Bit0	13	1	PCI0

**Byte 4: Output Enable Register**

(1 = enable, 0 = Tristate)

Bit	Pin #	PUP	Description
Bit7	-	1	RESERVED
Bit6	-	1	RESERVED
Bit5	-	1	RESERVED
Bit4	-	1	RESERVED
Bit3	-	1	RESERVED
Bit2	-	1	REF2_50M (1= ENABLE, 0=Tri state)
Bit1	-	1	REF1 (1= ENABLE, 0=Tri state)
Bit0	-	1	REF0 (1= ENABLE, 0=Tri state)

Byte 5: Reserved

Bit	Pin #	PUP	Description
Bit7	X	X	RESERVED
Bit6	X	1	RESERVED
Bit5	X	1	RESERVED
Bit4	X	1	RESERVED
Bit3	X	1	RESERVED
Bit2	X	1	RESERVED
Bit1	X	1	RESERVED
Bit0	X	1	RESERVED

Byte 6: Vendor ID Register

(1 = enable, 0 = disable)

Bit	Name	PUP	Description
Bit 7	Revision ID Bit3	0	Revision ID values will be based on individual device revisions
Bit 6	Revision ID Bit 2	0	
Bit 5	Revision ID Bit1	0	
Bit 4	Revision ID Bit0	0	
Bit 3	Vendor ID Bit3	0	RESERVED
Bit 2	Vendor ID Bit2	0	RESERVED
Bit 1	Vendor ID Bit1	0	RESERVED
Bit 0	Vendor ID Bit0	1	ICS

**Byte 7: Revision ID and Device ID Register**

(1 = enable, 0 = disable)

Bit	Name	PUP	Description
Bit 7	Device ID7	0	Device ID values will be based on individual device "02" in this case
Bit 6	Device ID6	0	
Bit 5	Device ID5	0	
Bit 4	Device ID4	0	
Bit 3	Device ID3	0	
Bit 2	Device ID2	0	
Bit 1	Device ID1	1	
Bit 0	Device ID0	0	

Byte 8: Byte Count and Readback Register.

Bit	Name	PUP	Description
Bit 7	Byte7	0	Note: Writing to this register will configure byte count and how many bytes will be read back. Default is 0F _H = 15 bytes
Bit 6	Byte6	0	
Bit 5	Byte5	0	
Bit 4	Byte4	0	
Bit 3	Byte3	1	
Bit 2	Byte2	1	
Bit 1	Byte1	1	
Bit 0	Byte0	1	

Byte 9: Watchdog Timer Count Register

Bit	Name	PUP	Description
Bit 7	WD7	0	RESERVED
Bit 6	WD6	0	
Bit 5	WD5	0	
Bit 4	WD4	1	
Bit 3	WD3	0	
Bit 2	WD2	0	
Bit 1	WD1	0	
Bit 0	WD0	0	

**Byte 10: Programming Enable Register**

Bit	Name	PUP	Description
Bit 7	M/N Program Enable	0	Programming Enable bit 0 = no programming. Frequencies are selected by HW latches or by Byte 0, 1 = enable all SMBUS programming
Bit 6	WD Enable	0	RESERVED
Bit 5	WD Alarm	0	RESERVED
Bit 4	-	-	RESERVED
Bit 3	-	-	
Bit 2	-	-	
Bit 1	-	-	
Bit 0	-	-	

Byte 11: VCO Frequency M Divider (Reference divider) Control Register

Bit	Name	PUP	Description
Bit 7	Ndiv8	X	N divider bit 8
Bit 6	Mdiv6	X	The decimal representation of Mdiv (6:0) corresponds to the reference divider value. Default at power up is equal to the latched inputs selection.
Bit 5	Mdiv5	X	
Bit 4	Mdiv4	X	
Bit 3	Mdiv3	X	
Bit 2	Mdiv2	X	
Bit 1	Mdiv1	X	
Bit 0	Mdiv0	X	

Byte 12: VCO Frequency N Divider (VCO divider) Control Register

Bit	Name	PUP	Description
Bit 7	Ndiv7	X	The decimal representation of Ndiv (7:0) corresponds to the VCO divider value. Default at power up is equal to the latched inputs selection. Notice Ndiv 8 is located in Byte 11.
Bit 6	Ndiv6	X	
Bit 5	Ndiv5	X	
Bit 4	Ndiv4	X	
Bit 3	Ndiv3	X	
Bit 2	Ndiv2	X	
Bit 1	Ndiv1	X	
Bit 0	Ndiv0	X	

**Byte 13: Spread Spectrum Control Register**

Bit	Name	PUP	Description
Bit 7	SS 7	X	The Spread Spectrum (13:0) (or see Byte 14) bit will program the spread percentage. Spread percent needs to be calculated based on the VCO frequency, spreading profile, spreading amount, and spread frequency. It is recommended to use ICS software for spread programming. Default power on is latched FS divider.
Bit 6	SS 6	X	
Bit 5	SS 5	X	
Bit 4	SS 4	X	
Bit 3	SS 3	X	
Bit 2	SS 2	X	
Bit 1	SS 1	X	
Bit 0	SS 0	X	

Byte 14: Spread Spectrum Control Register

Bit	Name	PUP	Description
Bit 7	RESERVED	X	RESERVED
Bit 6	RESERVED	X	RESERVED
Bit 5	SS 13	X	Spread Spectrum Bit 13
Bit 4	SS 12	X	Spread Spectrum Bit 12
Bit 3	SS 11	X	Spread Spectrum Bit 11
Bit 2	SS 10	X	Spread Spectrum Bit 10
Bit 1	SS 9	X	Spread Spectrum Bit 9
Bit 0	SS 8	X	Spread Spectrum Bit 8

Byte 15: Output Divider Control Register

Bit	Name	PUP	Description
Bit 7	DDR Div 3	X	DDRC clock divider ratio can be configured via these four bits individually. For divider selection table, refer to Table 1. Default at power up is latched FS divider.
Bit 6	DDR Div 2	X	
Bit 5	DDR Div 1	X	
Bit 4	DDR Div 0	X	
Bit 3	CPU Div 3	X	CPU clock divider ratio can be configured via these four bits individually. For divider selection table refer to Table 1. Default at power up is latched FS divider.
Bit 2	CPU Div 2	X	
Bit 1	CPU Div 1	X	
Bit 0	CPU Div 0	X	

**Byte 16: Output Divider Control Register**

Bit	Name	PUP	Description
Bit 7	PCI Div 3	X	PCI clock divider ratio can be configured via these four bits individually. For divider selection table, refer to Table 2. Default at power up is latched FS divider.
Bit 6	PCI Div 2	X	
Bit 5	PCI Div 1	X	
Bit 4	PCI Div 0	X	
Bit 3		X	RESERVED
Bit 2		X	
Bit 1		X	
Bit 0		X	

Byte 17: Output Divider Control Register

Bit	Name	PUP	Description
Bit 7	PCI_XINV	X	PCI_X Phase Inversion bit
Bit 6	PCI_INV	X	PCI Phase Inversion bit
Bit 5	DDR_INV	X	DDR Phase Inversion bit
Bit 4	CPU_INV	X	CPUCLK Phase Inversion bit
Bit 3	PCI_XDiv 3	X	PCI clock divider ratio can be configured via these
Bit 2	PCI_XDiv 2	X	
Bit 1	PCI_XDiv 1	X	
Bit 0	PCI_X Div 0	X	

Table 1 CPU/DDR Output Divide

Div (3:2)	Div (1:0)			
	00	01	10	11
00	/2	/4	/8	/16
01	/3	/6	/12	/24
10	/5	/10	/20	/40
11	/9	/18	/36	/72

Table 2 PCI/PCI_X Output Divide

Div (3:2)	Div (1:0)			
	00	01	10	11
00	/2	/4	/8	/16
01	/3	/6	/12	/24
10	/9	/18	/36	/72
11	/15	/30	/60	/120

**Byte 18: Group Skew Control Register**

Bit	Name	PWD	Programming Sequence				
Bit 7	RESERVED	0	0	0	0	0	0ps
Bit 6		0	0	1	0	0	150ps
Bit 5		0	1	0	0	0	300ps
Bit 4		0	1	1	0	0	450ps
Bit 3	These four bits control all clocks to CPU (1:0)	0	1	1	0	1	600ps
Bit 2		0	1	1	1	0	750ps
Bit 1		0	1	1	1	1	900ps
Bit 0		0	Reserved				

Byte 19: Group Skew Control Register

Bit	Name	PWD	Programming Sequence				
Bit 7	These four bits control DDR (5:0)	0	0	0	0	0	0ps
Bit 6		0	0	1	0	0	150ps
Bit 5		0	1	0	0	0	300ps
Bit 4		0	1	1	0	0	450ps
Bit 3	These four bits control PCI (3:0)	0	1	1	0	1	600ps
Bit 2		0	1	1	1	0	750ps
Bit 1		0	1	1	1	1	900ps
Bit 0		0	Reserved				

Byte 20: Slew Rate Control Register

Bit	Name	PWD	Programming Sequence				
Bit 7	These four bits control Skew PCI_X:0)	0	0	0	0	0	0ps
Bit 6		0	0	1	0	0	150ps
Bit 5		0	1	0	0	0	300ps
Bit 4		0	1	1	0	0	450ps
Bit 3	RESERVED	0	1	1	0	1	600ps
Bit 2		0	1	1	1	0	750ps
Bit 1		0	1	1	1	1	900ps
Bit 0		0	Reserved				

**Byte 21: Slew Rate Control Register**

Bit	Name	PUP	Description
Bit 7	REF0	0	Clock slew rate control bits. 01 = strong: 11 = 00 medium: 10 = weak
Bit 6		1	
Bit 5	RESERVED	X	RESERVED
Bit 4	RESERVED	X	RESERVED
Bit 3	PCI (1:0)	0	Clock slew rate control bits. (00=0.7X, 01=0.8X, 10=0.90X, 11=1.0X)
Bit 2		1	
Bit 1	PCI (3:2)	0	Clock skew rate control bits. (00=0.7X, 01=0.8X, 10=0.90X, 11=1.0X)
Bit 0		1	

Byte 22: Slew Rate Control Register

Bit	Name	PUP	Description
Bit 7	PCI_X6	0	Clock slew rate control bits. AGP Phase Inversion bit
Bit 6		1	
Bit 5	PCI_X(5)	0	Clock slew rate control bits. (00=0.63X, 01=0.75X, 10=0.88X, 11=1.0X)
Bit 4		1	
Bit 3	PCI_X(4:3:2)	0	Clock slew rate control bits. (00=0.63X, 01=0.75X, 10=0.88X, 11=1.0X)
Bit 2		1	
Bit 1	PCI_X(1:0)	0	Clock slew rate control bits. (00=0.63X, 01=0.75X, 10=0.88X, 11=1.0X)
Bit 0		1	

**Note for PCI_X frequency selection of 133.33 MHz
use 11=1.0X buffer s.**

Byte 23: Slew Rate Control Register

Bit	Name	PUP	Description
Bit 7	RESERVED	X	RESERVED
Bit 6		X	
Bit 5	RESERVED	X	RESERVED
Bit 4		X	
Bit 3	IREFSGL	1	00 = 5x, 01 = 4x, 10 = 6x, 11 = 7x
Bit 2		0	
Bit 1	REF_50M	0	Clock slew rate control bits. 01 = strong: 11 = 00 medium: 10 = weak
Bit 0		1	



External Components

The MK1493-02A requires a minimum number of external components for proper operation.

Decoupling Capacitor

Decoupling Capacitors of 0.1 μ F and 0.001 μ F must be connected between each VDD and GND as close to the device as possible. For optimum device performance, the decoupling capacitor should be mounted on the component side of the PCB. Avoid the use of vias in the decoupling circuit.

Series Termination Resistor

When the PCB trace between the clock outputs and the loads are over one inch, series termination should be used. To series terminate a 50 Ω trace (a commonly used trace impedance), place a 33 Ω resistor in series with the clock line as close to the clock output pin as

possible. The nominal impedance of the clock output is 20 Ohms.

Crystal Information

The crystal used should be a fundamental mode, parallel resonant crystal. Do not use third overtone. Crystal capacitors should be connected from pins X1 to ground and from X2 to ground to optimize the initial accuracy. The value of these capacitors is given by the following equation:

$$\text{Crystal caps (pF)} = (C_L - 6) \times 2$$

In the equation, C_L is the crystal load capacitance. So for a crystal with 16 pF load capacitance, two 20 pF [(1606) x 2] capacitors should be used.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the MK1493-02A. These ratings are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	5.5 V
All Inputs and Outputs	-0.5 V to VDD+0.5 V
Ambient Operating Temperature	0 to +70°C
Storage Temperature	-65 to +150°C
Junction Temperature	125°C
Soldering Temperature	260°C

**Electrical Characteristics - Input/Supply/Common Output Parameters**Unless stated otherwise, **VDD = 3.3 V ±5%**, Ambient Temperature 0 to +75°C

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input High Voltage	V_{IH}		2.4		VDD +0.3	V
Input Low Voltage	V_{IL}		-0.3		0.8	V
Input High Current	I_{IH}	$V_{IN} = V_{DD}$	-5		5	mA
Input Low Current	I_{IL1}	$V_{IN} = 0V$; Inputs w/no pull-up resistors	-5			mA
	I_{IL2}	$V_{IN} = 0V$; Inputs with pull-up resistors	-200			mA
Operating Supply Current	I_{DD}	CL = 0pF; Select @ 66M		135		mA
		CL = full load		325		mA
Pin Inductance	L_{pin}				7	nH
Input Capacitance	C_{IN}	Logic inputs			5	pF
	C_{OUT}	Output pin capacitance			6	pF
Transition Time	T_{trans}	To 1st crossing of target frequency			3	ms
Setting Time	T_S	From 1st crossing to 1% target frequency			3	ms
Clock Stabilization	T_{STAB}	From $V_{DD} = 3.3 V$ to 1% target frequency			3	ms
Delay	t_{PZH}, t_{PZH}	output enable delay (all outputs)	1		10	ns
	t_{PLZ}, t_{PZH}	output disable delay (all outputs)	1		10	ns
Modulation Frequency			28		33	kHz
Rise Time	t_{RISE}	OE, CLKSTPB, PCISTPB			5	ns
Fall Time	t_{FALL}	OE, CLKSTPB, PCISTPB			5	ns
SMBUS Voltage	V_{DD}		2.7		5.5	V
Low-Level Output Voltage	V_{OL}				0.4	V
Current Sinking	I_{pullup}	$V_{OL} = 0.4 V$	4			mA
SCLK/SDATA CLK/Data Rise Time	T_{RI}	Max $V_{IL}-0.15$ to Min $V_{IH}+0.15$			1000	ns
SCLK/SDATA CLK/Data Fall Time	T_{FI}	Max $V_{IL}-0.15$ to Min $V_{IH}+0.15$			300	ns
OE Enable Time		tri state to active output after powerup			10	ns
OE Disable Time		Active data to tri state, after powerup			10	ns



Electrical Characteristics - CPU 0.7V Current Mode Differential Pair

Unless stated otherwise, **VDD = 3.3 V ±5%**, Ambient Temperature 0 to +70°C, $C_L = 2$ pF

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Current Source Output Impedance	Z_O	$V_O = V_X$	3000			Ω
Voltage High	V_{HIGH}	Statistical measurement on a single ended signal using oscilloscope math function	660	770	850	mV
Voltage Low	V_{LOW}		-150	5	150	
Max Voltage	V_{OVS}	Measurement on single ended signal using absolute value		756	1150	mV
Min Voltage	V_{UDS}		-300	-7		mV
Crossing Voltage (abs)	V_{ABS}	Absolute value of crossing Voltage	250	350	550	mV
Crossing Voltage (variation)	V_{CROSS}	Variation of crossing over all edges		12	140	mV
Rise Time	t_{RISE}	$V_{OL} = 0.175$ V, $V_{OH} = 0.525$ V	175	332	700	ps
Fall Time	t_{FALL}	$V_{OL} = 0.175$ V, $V_{OH} = 0.525$ V	175	344	700	ps
Rise Time Variation	$d-t_{RISE}$			30	125	ps
Fall Time Variation	$d-t_{FALL}$			30	125	ps
Duty Cycle		Measurement from differential wave forms	45	49	55	%
Skew		$V_T = 50\%$ (measurement threshold)			100	ps
Jitter, Cycle to Cycle		Measurement from differential wave forms		60	125	ps

Electrical Characteristics - PCI_XCLK

Unless stated otherwise, **VDD = 3.3 V ±5%**, Ambient Temperature 0 to +70°C, $C_L = 10-30$ pF

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Output Frequency			33.33		133.33	MHz
Output Impedance		$V_O = V_{DD} * (0.5)$	12		55	Ω
Output High Voltage	V_{OH1}	$I_{OH} = -1$ mA	2.4			V
Output Low Voltage	V_{OL1}	$I_{OL} = 1$ mA			0.55	V
Output High Current	I_{OH1}	$V_{OH@MIN} = 1.0$ V, $V_{OH@MAX} = 3.135$ V	-33		-33	mA
Output Low Current	I_{OL1}	$V_{OL@MIN} = 1.95$ V, $V_{OL@MAX} = 0.4$ V	30		38	mA
Rise Time	t_{RISE}	$V_{OL} = 0.4$ V, $V_{OH} = 2.4$ V	0.5		3	ns
Fall Time	t_{FALL}	$V_{OH} = 2.4$ V, $V_{OL} = 0.4$ V	0.5		2	ns
Duty Cycle		$V_T = 1.5$ V	45		55	%
Skew		$V_T = 1.5$ V			200	ps
Jitter PCI (6:0)		$V_T = 1.5$ V			250	ps



Electrical Characteristics/DDR Buffers - Input/Supply/Common Output Parameters

Unless stated otherwise, $V_{DD} = 2.5\text{ V} \pm 0.2\text{ V}$, Ambient Temperature 0 to +75°C

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Analog /core supply Voltage	V_{DD}, A_{VDD}		2.3	2.5	2.7	
Operating Supply Current	I_{DD}	$C_L = 0\text{pF}$; Select @ 133M		245	300	mA
High Impedance Output Current	I_{OZ}	$V_{DD} = 2.7\text{ V}$, $V_{OUT} = V_{DD}$ or GND			10	μA
Input Clamp Voltage	V_{IK}	$I_{in} = -18\text{ mA}$			-1.2	V
High Level Output Voltage	V_{OH}	$V_{DD} = \text{min to max}$, $I_{OH} = -1\text{ mA}$	2.1	2.42		V
		$V_{DD} = 2.3\text{ V}$, $I_{OH} = -12\text{ mA}$	1.7	1.87		V
Low Level Output Voltage	V_{OL}	$V_{DD} = \text{min to max}$, $I_{OL} = 1\text{ mA}$		0.04	0.1	V
		$V_{DD} = 2.3\text{ V}$, $I_{OL} = 12\text{ mA}$		0.35	0.6	V
Input Capacitance	C_{IN}	$V_I = V_{DD}$ or GND				pF
Output Capacitance	C_{OUT}	$V_I = V_{DD}$ or GND		3		pF
Input Voltage leve	VIL				$V_{DD}/2-0.5\text{ V}$	V
Input Voltage level	VIH		$V_{DD}/2+0.5\text{ V}$			V
Input Duty Cycle			40%		50%	
Input mac jitter					150	ps

Timing Requirements

Unless stated otherwise, $V_{DD} = 2.5\text{ V} \pm 0.2\text{ V}$, Ambient Temperature 0 to +70°C

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Clock Frequency			33.33		200	MHz
Input Clock Duty Cycle			40		60	%
Clock Stabilization	t_{STAB}	from $V_{DD} = 2.5\text{ V}$ to 1% target freq.			3	ms

Switching Characteristics

Unless stated otherwise, $V_{DD} = 2.5\text{ V} \pm 0.2\text{ V}$, Ambient Temperature 0 to +70°C

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Absolute Jitter	t_{jabs}	33 MHz			120	ps
		100/125/133/150/167/200 MHz			100	ps
Cycle to cycle jitter		33 MHz		50	110	ps
		100/125/133/150/167 MHz		60	100	ps
Output to output Skew		with input clock 0-2.5 V 0.8 ns rise/fall		40	100	ps
Duty Cycle (differential) ¹	D_C	no loads, 66 MHz to 167 MHz	47	50	53	%
Rise Time, Fall Time	t_{RISE}, t_{FALL}	Single-ended 20 - 80%; Load = 120 Ω /12 pF	450	550	950	ps



¹ While the pulse skew is almost constant over frequency, the duty cycle error increases at higher frequencies. This is due to the formula: duty cycle = t_{WH}/t_C , where the cycle time (t_C) decreases as the frequency increases.

Electrical Characteristics - PCI

Unless stated otherwise, VDD = 3.3 V \pm 5%, Ambient Temperature 0 to +70°C, C_L = 10 - 30 pF

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Output Frequency	F _O		33.33		66.66	MHz
Output Impedance	R _{DSP}	V _O = V _{DD} *0.5	12		55	W
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4			V
Output Low Voltage	V _{OL}	I _{OL} = 1 mA			0.4	V
Output High Current	I _{OH}	V _{OH} @MIN = 1.0 V, V _{OH} @MAX = 3.135 V	-33		-33	mA
Output Low Current	I _{OL}	V _{OH} @MIN = 1.95 V, V _{OH} @MAX = 0.4 V	30		38	mA
Rise Time	T _{RISE}	V _{OL} = 0.4 V, V _{OH} = 2.4 V	0.5		2	ns
Fall Time	T _{FALL}	V _{OH} = 2.4 V, V _{OL} = 0.4 V	0.5		2	ns
Duty Cycle	d _t	V _T = 1.5 V	45		55	%
Skew	t _{SK}	V _T = 1.5 V			100	ps
Jitter		V _T = 1.5 V			300	ps

Electrical Characteristics - 50 MHz (pin 4)

Unless stated otherwise, VDD = 3.3 V \pm 5%, Ambient Temperature 0 to +70°C, C_L = 10 - 30 pF

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4			V
Output Low Voltage	V _{OL}	I _{OL} = 1 mA			0.55	V
Output High Current	I _{OH}	V _{OH} @MIN = 1.0 V, V _{OH} @MAX = 3.135 V	-29		-23	mA
Output Low Current	I _{OL}	V _{OH} @MIN = 1.95 V, V _{OH} @MAX = 0.4 V	29		27	mA
Rise Time	T _{RISE}	V _{OL} = 0.4 V, V _{OH} = 2.4 V			2.0	ns
Fall Time	T _{FALL}	V _{OH} = 2.4 V, V _{OL} = 0.4 V			1.8	ns
Duty Cycle	d _t	V _T = 1.5 V	45		55	%
Jitter		V _T = 1.5 V			400	ps

Electrical Characteristics - REF(Pins 7,8)

Unless stated otherwise, **VDD = 3.3V ±5%**, Ambient Temperature 0 to +70°C, $C_L = 10 - 30$ pF

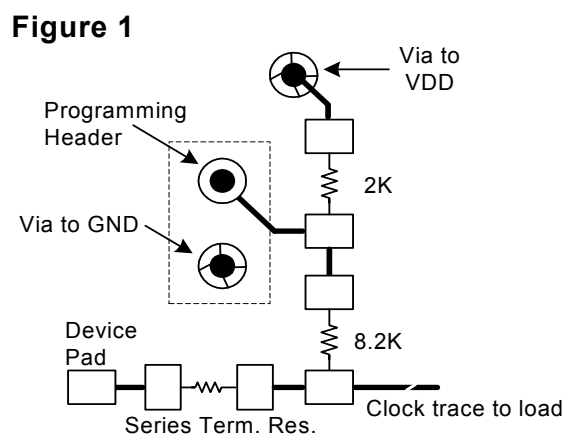
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Output Impedance	R_{DSP}	$V_O = V_{DD} * 0.5$	20		60	Ω
Output High Voltage	V_{OH}	$I_{OH} = -1$ mA	2.4			V
Output Low Voltage	V_{OL}	$I_{OL} = 1$ mA			0.4	V
Output High Current	I_{OH}	$V_{OH@MIN} = 1.0$ V, $V_{OH@MAX} = 3.135$ V	-29		-23	mA
Output Low Current	I_{OL}	$V_{OH@MIN} = 1.95$ V, $V_{OH@MAX} = 0.4$ V	29		27	mA
Rise Time	T_{RISE}	$V_{OL} = 0.4$ V, $V_{OH} = 2.4$ V		2		ns
Fall Time	T_{FALL}	$V_{OH} = 2.4$ V, $V_{OL} = 0.4$ V		1.8		ns
Duty Cycle	d_t	$V_T = 1.5$ V	45		55	%
Skew	t_{SK}	$V_T = 1.5$ V		70		ps
Jitter		$V_T = 1.5$ V			1000	ps

Shared Pin Operation - Input/Output Pins

The I/O pins designated by (input/output) serve as dual signal functions to the device. During initial power up, they act as input pins. The logic level (voltage) that is present on these pins at this time is read and stored into a five-bit internal data latch. At the end of Power-on reset, (see AC characteristics for timing values), the device changes the mode of operations for these pins to an output function. In this mode, the pins produce the specified buffered clocks to external loads.

To program (load) the internal configuration register for these pins, a resistor is connected to either the VDD (logic 1) power supply or the GND (logic 0) voltage potential. A 10 kilohm (10K) resistor is used to provide both the solid CMOS programming voltage needed during the power-up programming period and to provide an insignificant load on the output clock during the subsequent operation period.

Figure 1 shows a means of implementing this function when a switch or 2 pin header is used. With no jumper installed, the pin will be pulled high. With the jumper in place, the pin will be pulled low. If programmability is not necessary, then only a single resistor is necessary. The programming resistors should be located close to the series termination resistor to minimize the current loop area. It is more important to place the series termination resistor close to the driver than to the programming resistor.





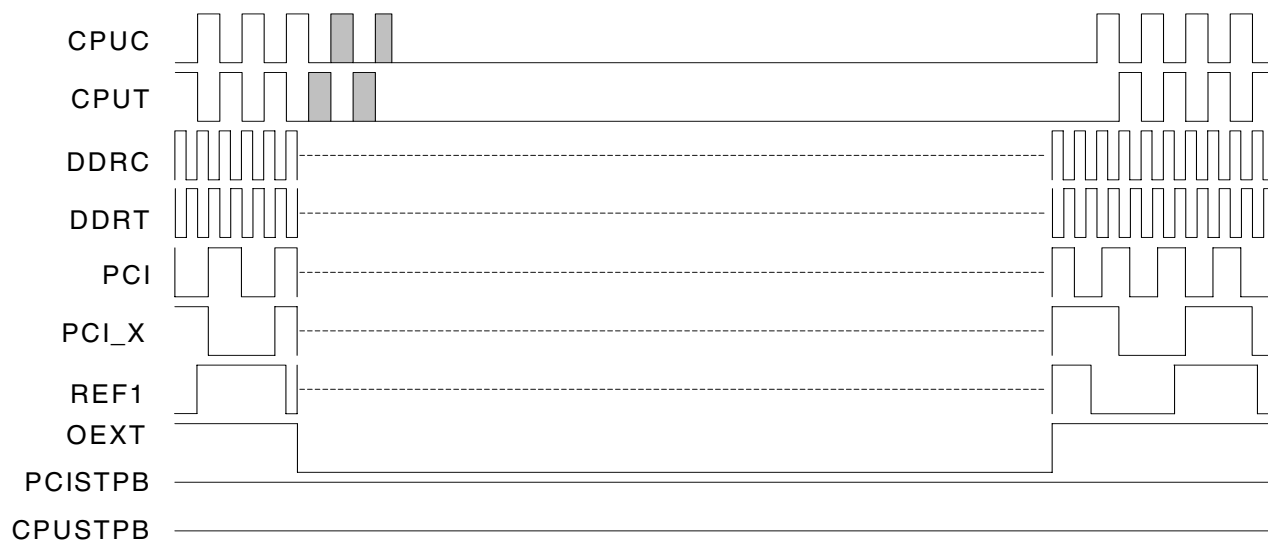
OE - ASSERTION (transition from logic “1” to logic “0”)

When the asynchronous OE pin is pulled low, the REF clocks, PCI clocks, PCI_XClocks, the DDRT/C Clocks, are tristated in 20 ns. The CPUT/C clocks are pulled low. See waveform 1.

OE - DEASSERTION (transition from logic “0” to logic “1”)

When the asynchronous OE pin is pulled high, the REF clocks, PCI clocks, PCI_X Clocks, DDRT/C Clocks, and the CPUT/C clock are enabled in 20 ns. See waveform 1.

Waveform 1





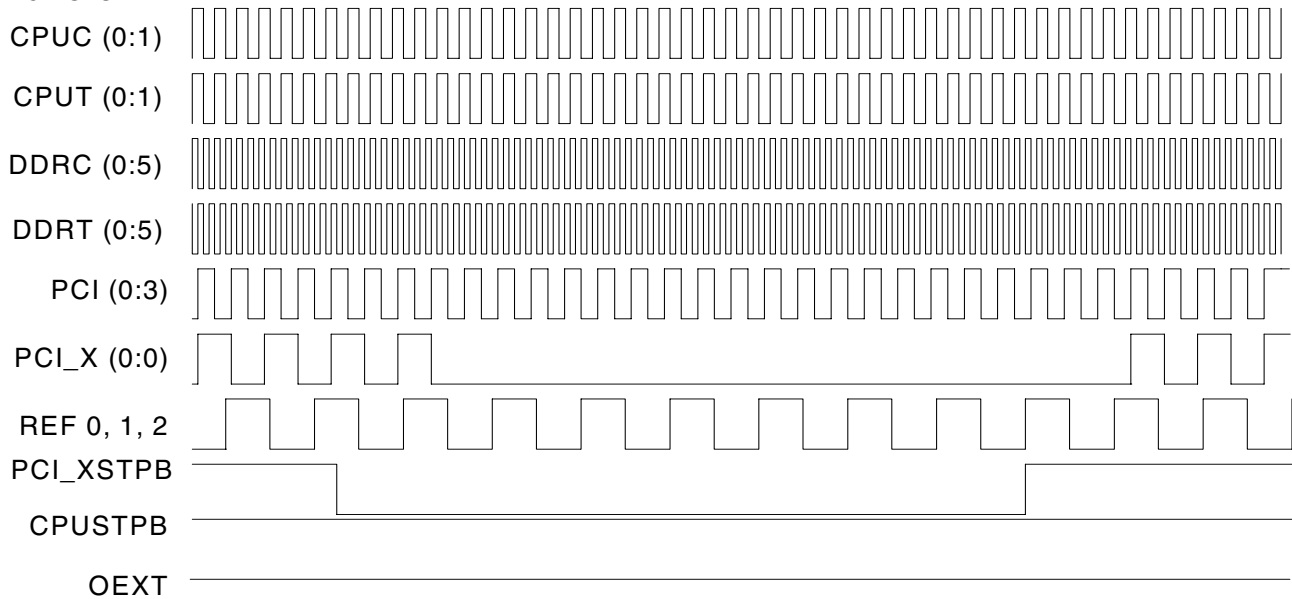
PCI_XSTPB Input Timing - ASSERTION (transition from logic “1” to logic “0”)

When the input of the PCI_XSTPB signal is pulled low, PCI_X (6:0) outputs are latched low in their next high to low transition. The PCI_XSTPB set up time is 10ns for the transitions to be recognized by the next rising edge (see waveform 2; one cycle latency). All other waveforms are not affected. This timing assumes that the seven PCI_X outputs are enabled via Byte 2 (bits 0:6). See waveform 2.

PCI_XSTPB - DEASSERTION (transition from logic “0” to logic “1”)

When the PCI_XSTPB signal is pulled high, the PCI_X signals are enabled after a setup time of 10 ns with a one cycle latency (see waveform 2). All PCI_X outputs are enabled via Byte 2 (bits 0:6).

Waveform 2





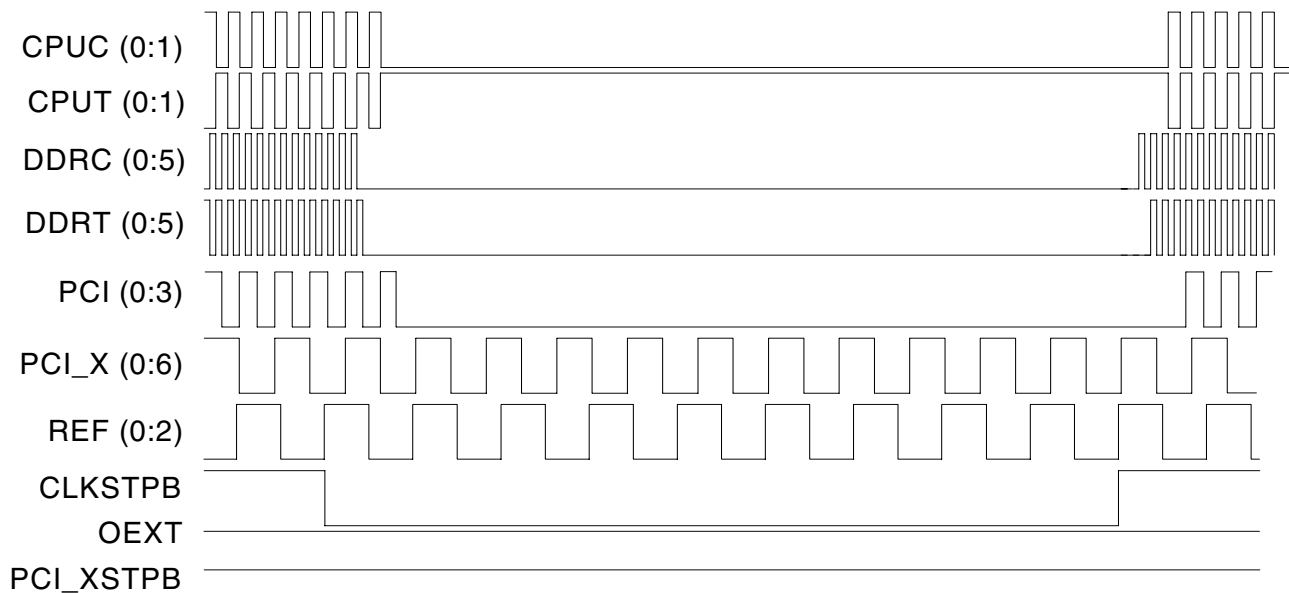
CLK_STPB - Assertion (transition from logic “0” to logic “1”)

When this asynchronous input is pulled low, all clocks (CPUT/C, DDRT/C, PCI) are pulled low with a two cycle latency. See waveform 3. This condition assumes all CPUT/C, DDRT/C, and PCI clocks are enabled via Byte 3 (Bit 5, Bit 6), Byte 3 (Bit 0, 1, 2, 3, 5, 6, 7). The set up time is 10 ns.

CLK_STPB - Deassertion (transition from logic “1” to logic “0”)

When this asynchronous input is pulled high, all clocks (CPUT/C, DDRT/C, PCI) are enabled after a setup time of 10 ns and two cycle latency. See waveform 3. The waveform assumes that the CPUT/C, DDRT/C, and PCI clocks are enabled via Byte 1 (Bit 5, Bit 6), Byte 3 (Bit 0, 1, 2, 3, 5, 6, 7). The set up time is 10 ns.

Waveform 3



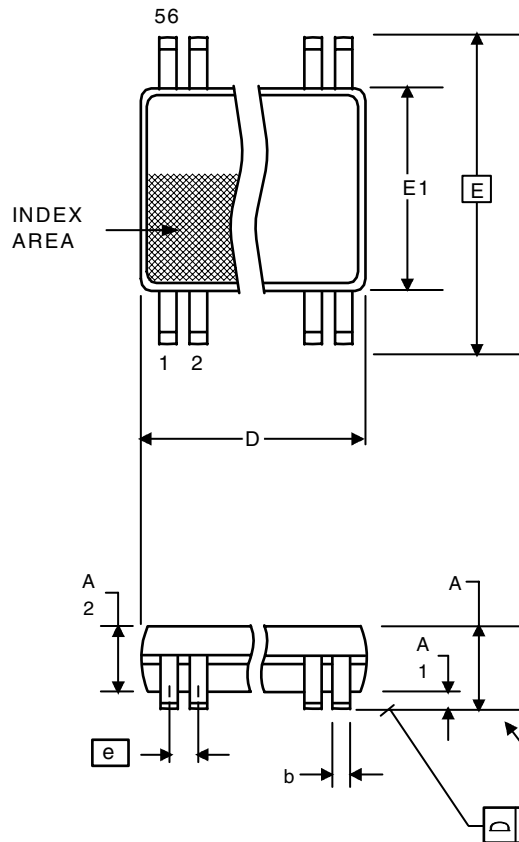
IREF

If board target trace impedance (Z) is 50Ω, then $R_r = 475\Omega$ (1%), providing IREF of 2.32 mA, output current (I_{OH}) is equal to $6 \cdot I_{REF}$.

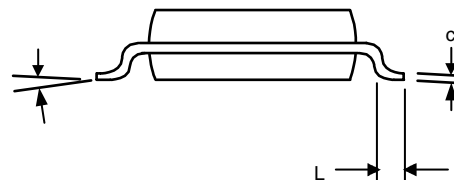
Package Outline and Package Dimension

56-pin TSSOP 6.10 mm (240 mil) body, 0.50 mm. (20 mil) pitch

Package dimensions are kept current with JEDEC Publication No. 95



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	--	1.20	--	0.047
A1	0.05	0.15	0.002	0.006
A2	0.80	1.05	0.032	0.041
b	0.17	0.27	0.007	0.011
C	0.09	0.20	0.0035	0.008
D	13.90	14.10	0.547	0.555
E	8.10 BASIC		0.319 BASIC	
E1	6.00	6.20	0.236	0.244
e	0.50 Basic		0.020 Basic	
L	0.45	0.75	0.018	0.030
α	0°	8°	0°	8°
aaa	--	0.10	--	0.004



Ordering Information

Part / Order Number	Marking	Shipping packaging	Package	Temperature
MK1493-02AG	MK1493-02AG	Tubes	56-pin TSSOP	0 to +70° C
MK1493-02AGTR	MK1493-02AG	Tape and Reel	56-pin TSSOP	0 to +70° C

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